

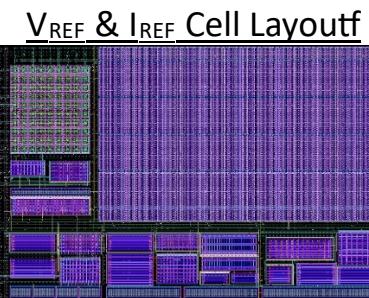
# VREF7

(internal #chip2\_VBGF)

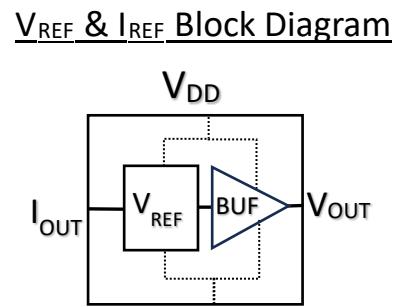
Fractional Bandgap Voltage & Current Reference with low TC. Proof of silicon with typical/preliminary measurements available. Please contact [sales@ailinear.com](mailto:sales@ailinear.com) for details & order specific evaluation

Parameter	Typical Spec	Condition
I <sub>DD</sub> (nA)	~330	V <sub>DD</sub> =1v, Temperature = 27C
V <sub>DD</sub> Low (v)	~0.8	V <sub>DD</sub> sweep 0v→1.1v, Temperature = 27C
V <sub>DD</sub> High (v)	~1	V <sub>DD</sub> sweep 0v→1.1v, Temperature = 27C
V <sub>REF</sub> OUT (v)	~0.63	V <sub>DD</sub> =1v, Temperature = 27C
I <sub>REF</sub> OUT (v)	~50	V <sub>DD</sub> =1v, Temperature = 27C
V <sub>REF</sub> TC (PPM/C)	TBD	Test in progress
I <sub>REF</sub> TC (PPM/C)	TBD	Test in progress
V <sub>REF</sub> PSRR (dB)	TBD	Test in progress

\*See Disclaimer\*



V<sub>REF</sub> & I<sub>REF</sub> Cell Size ~200μm×130 μm in TSMC 65nm CMOS



## Features:

- CMOS (~200μm×130 μm) fractional bandgap voltage and current reference (V<sub>REF</sub> ≈ V<sub>OUT</sub> ≈ 0.5V<sub>BG</sub> ≈ 0.63 & typ. I<sub>REF</sub> ≈ I<sub>OUT</sub> ≈ 50nA) Intellectual Property (IP) cell operates in subthreshold with low I<sub>DD</sub> (typical 330nA)
- Trimmable or Programmable (pre or post silicon) absolute value of V<sub>REF</sub> & I<sub>REF</sub>
- Trimmable or Programmable TC
- Equipped with start-up, and power-down
- V<sub>REF</sub> Includes an internal buffer (BUF) to drive larger loads (e.g. Mega Ωs) in a SoC
- No clock, no switch-capacitor, and no related noise or injections into substrate
- Utilizes a fractional bandgap topology to generate V<sub>REF</sub> & I<sub>REF</sub> through a bias resistor (R<sub>POLY</sub>)
- Operation at low V<sub>DD</sub> levels ≈V<sub>REF</sub> + 2V<sub>DS</sub>
- Suitable for SoC optimized for V<sub>REF</sub> & I<sub>REF</sub> fractional bandgap voltage loop that is coupled to V<sub>SS</sub>
- Utilizes parasitic (substrate) bipolar junction transistor (BJT) freely available in digital CMOS
- Based on 65nm digital CMOS at TSMC and portable to smaller fabrication nodes.